



**Product Change Notification**

**CN-202402003F**

**Issue date:** 23 Dec 2024

**Effective date:** 24 Mar 2025

Here's your personalized quality information concerning products our customers and partners purchased from Nexperia.

For more details please contact your respective Nexperia CSR/AM.



**Introduce additional subcon TFME (for selected TSSOP14/16) and BOM change in existing location ATXSZ (SO14/16 & TSSOP14/16/20)**

**Change Category**

- Wafer  Assembly
- Fab  Process  Product Marking  Test Location  Design
- Materials  Assembly  Mechanical  Test Process  Errata
- Location  Location  Packing/Shipping/Labeling  Test Equipment  Electrical spec./Test coverage

## Details of this change

Introduce additional Full Turnkey subcon TFME and BOM change in existing location ATXSZ to standardize and improve quality and support market growth and customer demand. (Phase 2).

- No change in form, fit, function, quality, workability and reliability anticipated.
- No impact on the product's functionality anticipated.
- No change in diffusion fab location or fab process (same die with same electrical distribution).
- No change in data sheet and test limits.
- No change in ordering code 12NC (sales part number).
- Phase 1 ATXSZ (communicated via PCN CN-202307004F) has been implemented.

Qualification\_Report\_PCN\_CN-202402003F.pdf:

[https://qcm.nexperia.com/Document/DOC-586924/Qualification\\_Report\\_PCN\\_CN-202402003F.pdf](https://qcm.nexperia.com/Document/DOC-586924/Qualification_Report_PCN_CN-202402003F.pdf)

### Why do we implement this change?

- Introduce 2nd source production location TFME to support market growth and secure contingency situation.
- To support increased customer demand.
- Order Lead-Time Improvement.
- Improved delamination performance.
- Supporting global efforts towards sustainability by reducing the use of so-called conflict minerals.

### Identification of affected products

Assembly location identifier on product marking and Product Manufacturing Code (PMC) on reel and box labels code 2nd character represent the assembly location, "X" for ATXSZ and "2" for TFME.

## Management summary

Nexperia is pleased to announce TFME (TongFu Microelectronics Co. Ltd. Nantong China) as additional location for assembly and test TSSOP14/16 Nexperia products. The existing assembly and test location ATXSX (ATX Semiconductors Suzhou China) will change BOM to secure standardization on product level.

## Product availability

### Production

Planned first shipment: 23 Mar 2025

### Sample information

Samples are available upon request

## Impact

No impact to the product's functionality anticipated

### Data sheet revision

No impact to existing datasheet

### Disposition of old products

Shipment of changed product to start after depletion existing materials.

### Feedback

Your acknowledgement of this change, conform JEDEC J-STD-046, is expected till 22 Jan 2025. Lack of acknowledgement of the PCN constitutes acceptance of the change.

## Additional information

[View Change Notification Online](#)

## Remarks

Assembly location indicator suffix on the product topside marking and on the reel and box label: "X"= ATXSZ (Nexperia Assembly and Test Plant Suzhou China) and "2"= TFME (TongFu Microelectronics Co. Ltd. Nantong China). Samples are available upon request via Helpdesk+ from BG IC Solutions sample store in Nijmegen the Netherlands. Maximum sample order 300 pieces per type for limited products.

## Contact and support

For all Quality Notification content inquiries, please contact your local Nexperia Sales Support Team.

For specific questions on this notice or the products affected please contact our specialist directly: [pcn@nexperia.com](mailto:pcn@nexperia.com)

In case of distribution, please contact your distribution partner.

## About Nexperia B.V.

We at Nexperia are the efficiency semiconductor company. We deliver over 90 billion products a year and as such service thousands of global customers, both directly and through our extensive network of channel partners. We are at the heart of billions of electronic devices in the Automotive, Mobile, Industrial, Consumer, Computing, and Communication Infrastructure segments.

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